

Technical Data  
Data Sheet 4963, Rev.-

## **SILICON SCHOTTKY RECTIFIER DIE**

### **Low Forward Voltage Drop (200 °C T<sub>J</sub> Operation)**

#### **Applications:**

- Switching Power Supply • Converters • Free-Wheeling Diodes • Polarity Protection Diode

#### **Features:**

- Soft Reverse Recovery at Low and High Temperature
- Low Forward Voltage Drop
- Low Reverse Leakage Current
- Low Power Loss, High Efficiency
- High Surge Capacity
- Guard Ring for Enhanced Durability and Long Term Reliability
- Guaranteed Reverse Avalanche Characteristics
- Electrically / Mechanically Stable during and after Packaging

#### **Maximum Ratings<sup>(1)</sup>:**

| Characteristics                                  | Symbol             | Condition                                                                                                        | Max.        | Units |
|--------------------------------------------------|--------------------|------------------------------------------------------------------------------------------------------------------|-------------|-------|
| Peak Inverse Voltage                             | V <sub>RWM</sub>   | -                                                                                                                | 150         | V     |
| Max. Average Forward Current                     | I <sub>F(AV)</sub> | 50% duty cycle, rectangular wave form                                                                            | 7.5         | A     |
| Max. Peak One Cycle Non-Repetitive Surge Current | I <sub>FSM</sub>   | 8.3 ms, half Sine wave <sup>(1)</sup>                                                                            | 140         | A     |
| Non-Repetitive Avalanche Energy                  | E <sub>AS</sub>    | T <sub>J</sub> = 25 °C, I <sub>AS</sub> = 2.0 A, L = 6.5 mH                                                      | 13.0        | mJ    |
| Repetitive Avalanche Current                     | I <sub>AR</sub>    | I <sub>AS</sub> decay linearly to 0 in 1 μs<br>f limited by T <sub>J</sub> max V <sub>A</sub> =1.5V <sub>R</sub> | 2.0         | A     |
| Max. Junction Temperature                        | T <sub>J</sub>     | -                                                                                                                | -65 to +200 | °C    |
| Max. Storage Temperature                         | T <sub>stg</sub>   | -                                                                                                                | -65 to +200 | °C    |

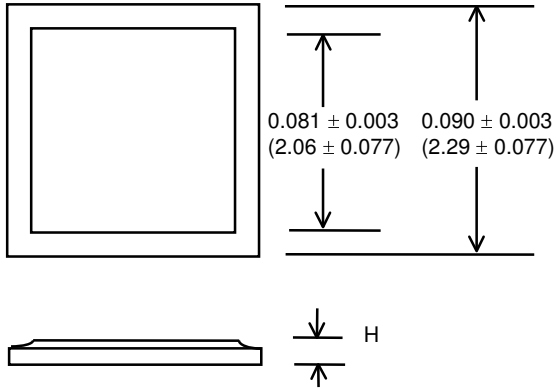
#### **Electrical Characteristics<sup>(1)</sup>:**

| Characteristics           | Symbol          | Condition                                                                                                 | Max. | Units |
|---------------------------|-----------------|-----------------------------------------------------------------------------------------------------------|------|-------|
| Max. Forward Voltage Drop | V <sub>F1</sub> | @ 7.5A, Pulse, T <sub>J</sub> = 25 °C                                                                     | 0.84 | V     |
|                           | V <sub>F2</sub> | @ 7.5A, Pulse, T <sub>J</sub> = 125 °C                                                                    | 0.68 | V     |
| Max. Reverse Current      | I <sub>R1</sub> | @V <sub>R</sub> = 150V, Pulse, T <sub>J</sub> = 25 °C                                                     | 0.25 | mA    |
|                           | I <sub>R2</sub> | @V <sub>R</sub> = 150V, Pulse, T <sub>J</sub> = 125 °C                                                    | 4.0  | mA    |
| Max. Junction Capacitance | C <sub>T</sub>  | @V <sub>R</sub> = 5V, T <sub>C</sub> = 25 °C<br>f <sub>SIG</sub> = 1MHz,<br>V <sub>SIG</sub> = 50mV (p-p) | 250  | pF    |

(1) in SHD package

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**Mechanical Dimensions: In Inches / mm**



Bottom side metalization Ag - 30 kÅ minimum.

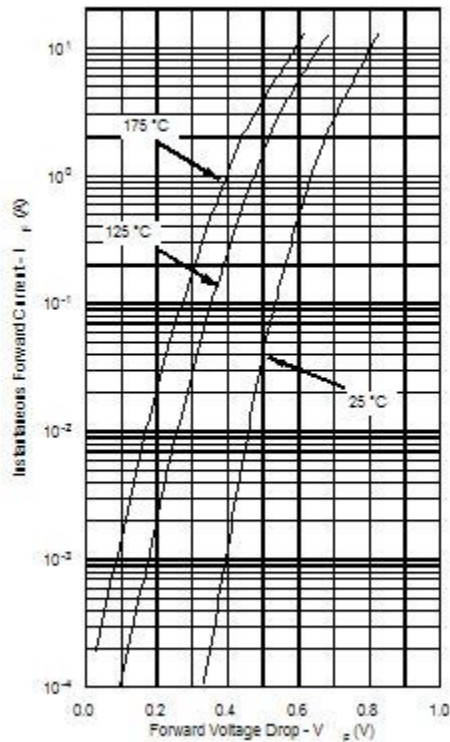
Top side metalization Al - 25 kÅ minimum  
or Ag - 30 kÅ minimum.

Bottom side is cathode, top side is anode.

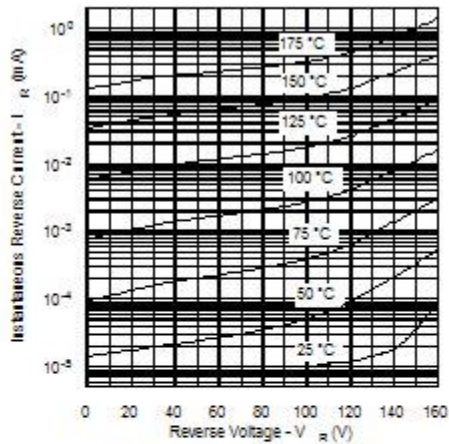
Dimension H =  $0.0105 \pm 0.001$  ( $0.27 \pm 0.026$ ) for Al top;

Dimension H =  $0.0155 \pm 0.001$  ( $0.39 \pm 0.026$ ) for Ag top.

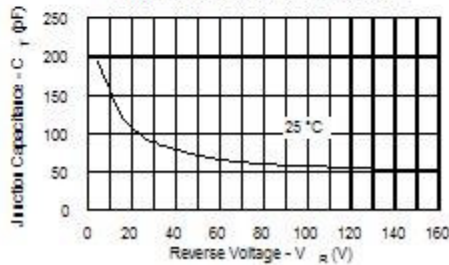
**Typical Forward Characteristics**



**Typical Reverse Characteristics**



**Typical Junction Capacitance**



**TECHNICAL DATA**

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